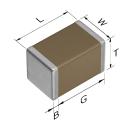
积层贴片陶瓷片式电容器

C2012X5R0J226M125AC

RoHS Reach Halogen Free Pb Free

交货型号	C2012X5R0J226MT****	
用途	一般等级	
特点	General 一般(~75V)	
系列	C2012 [EIA 0805]	
状态	作上生产计划 推荐代替型号 : <u>C2012X5R1A226M125AB</u> (不保证其兼容性。)	



尺寸		
长度(L)	2.00mm ±0.20mm	
宽度(W)	1.25mm ±0.20mm	
厚度(T)	1.25mm ±0.20mm	
端子宽度(B)	0.20mm Min.	
端子间隔(G)	0.50mm Min.	
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)	
1世存/产益41/四 (FA)	0.90mm to 1.20mm(Reflow Soldering)	
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)	
1647/大型が10/19 (LD)	0.70mm to 0.90mm(Reflow Soldering)	
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)	
1世代/产血作/四 U U/	0.90mm to 1.20mm(Reflow Soldering)	

	电气特性	
电容	$22~\mu\mathrm{F}~\pm20\%$	
额定电压	6. 3VDC	
温度特性	X5R(±15%)	
耗散因数(Max.)	15%	
绝缘电阻 (Min.)	4ΜΩ	

	其他	
焊接方法	流体	
件按刀伍	回流	
AEC-Q200	NO	
包装形式	塑封编带 (180mm卷筒)	
包装个数	2000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

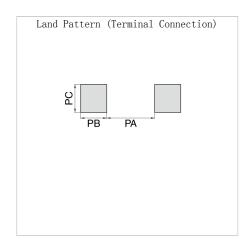
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Associated Images



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